



SDI Review Form 1.6

Journal Name:	Journal of Engineering Research and Reports
Manuscript Number:	Ms_JERR_50004
Title of the Manuscript:	A Study of Wafer Backgrinding Tape Selection for SOI Wafers
Type of the Article	Original Research Article

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Compulsory REVISION comments	It is interesting to study the quality index such as wafer breakage with regard to the adhesive contamination of different BG tapes But, the characterizations and explains about the examples and mechanism only depends on the simple description, and the more detailed mathematical model and measurement indexed should be given. More comments are as followings, 1) More references should be added to the introduction, and the methods to deal with the wafer warpage. 2) The indexes of Wafer warpage and etc. should be qualified. 3) What's the model of the wafer warpage and mechanical stress ...	
Minor REVISION comments		
Optional/General comments		

PART 2:

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	(If yes, Kindly please write down the ethical issues here in details)	

Reviewer Details:

Name:	Xingming Long
Department, University & Country	Chongqing Normal University, China